



Thermal conductive polyimide film is a polyamic acid resin made of a new formula of new anhydride monomer and new amine monomer . It is a new type of polyimide film produced by biaxial stretching process. It not only has all the excellent properties of ordinary polyamic acid film, but also has higher dimensional stability, high elastic modulus and good heat conduction ability.

I. Technical Requirements

1. Thickness and width

In Microns

Thickness	12.5	25
Tolerance	-1	-0.5
Width	≤520	≤520
Note: Thickness can also be provided according to user' s requirements		

2. Performance

Number	Index		Unit	Index value		
				12.5μm	25.0μm	
1	Tensile	Vertical, horizontal	Mpa	≥135		
				≥115		
2	Elongation	Vertical, horizontal	%	≥40		
3	Shrinkage	150°C	%	≤0.1		
		400°C		≤3.0		
4	Dielectric Strength	Average	MV/m	≥200	≥120	≥100
5	Thermal conductivity		W/m·k	≥0.35		
6	Volume Resistivity		Ωcm	≥1.0X10 ¹²		
	200°C					
7	Relative dielectric constant 48Hz~62Hz		—	3.0-3.5		
8	Dielectric loss factor 48Hz~62Hz		—	≤0.002		

II. Application

6051-MT thermal conductive polyimide film has high dimensional stability and similar CTE to copper foil, so it is especially suitable for manufacturing copper clad laminate in FPC industry. In particular to a heat-conducting double-sided flexible copper clad laminate. The thermal conductive polyimide film improves the thermal conductivity of flexible copper clad laminate, reduces the thermal resistance, enhances the thermal conductivity and heat dissipation capacity, and expands the application range.